

ABSTRACT

The present invention relates to an adhesive film capable of preventing damage to a non-metal-film-formed surface when forming a metal film on a semiconductor wafer and further capable of reducing contamination on the wafer surface. The adhesive film comprises a base film laminated with at least one film layer having a gas transmission rate of not more than $5.0 \text{ cc/m}^2 \cdot \text{day} \cdot \text{atm}$ with an adhesive layer formed on one surface thereof. By protecting the non-metal-film-formed surface, a washing step using a solvent can be omitted and contamination on the non-metal-film-formed surface can also be reduced, thus resulting in enhancement of productivity and workability.